

Specification Amendment

[0035] Referring to FIG. 2a, FIG. 2b, FIG. 2c, FIG. 2d and FIG. 2e a method for bonding an integrated circuit device to a glass substrate, of a first embodiment of this invention comprises the following steps. First, a glass substrate 20 is provided. After the glass substrate 10 is scribed and broken, as shown in step S11 of FIG. 2a, a melting device 30 is provided, and the melting device 30 melts a predetermined portion of the glass substrate 20, as shown in FIG. 2b and step S12 of FIG. 2a. It is noted that the predetermined portion of the glass substrate 20 is located at an edge of the glass substrate 20 in FIG. 2b. After performing the step S12, a rounded edge or radius ~~round-angle~~ 21 is formed at the edge of the glass substrate 20, as shown in FIG. 2c. Then, an integrated circuit device 40 is provided, and is bonded to the glass substrate 20, as shown in FIG. 2d and FIG. 2e and step S13 of FIG. 2a.